

App. No. 10/654,343
Office Action Dated May 10, 2006

Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Claim 15 is amended.

Listing of Claims:

1-14 (Canceled)

15. (Currently Amended) A method for manufacturing an electric element built-in module comprising:

flip-chip mounting at least one electric element that is a semiconductor chip, one of whose surface is provided with a functional portion and a connection electrode, on a wiring pattern so that the one surface faces the wiring pattern;

sealing the electric element with a thermosetting resin composition from a side of the other surface of the electric element; and

grinding or abrading the electric element sealed with the thermosetting resin composition from the side of the other surface of the electric element.

16. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein a bump is formed on the connection electrode of the electric element, and the electric element is mounted on the wiring pattern using the bump and an electrically conductive adhesive.

17. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein a bump is formed on the connection electrode of the electric element, and

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the electric element is mounted on the wiring pattern using the bump and a sheet in which an electrically conductive filler is dispersed.

18. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein a bump is formed on the connection electrode of the electric element, and the electric element is mounted on the wiring pattern by connecting the bump and the wiring pattern in an ultrasonic manner.

19. (Previously Presented) The method for manufacturing the electric element built-in module according to claim 15, further comprising filling and curing a resin between the electric element and the wiring pattern, after flip-chip mounting the electric element on the wiring pattern and before sealing the electric element with the thermosetting resin composition.

20. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein the electric element is sealed with the thermosetting resin composition by overlaying an uncured sheet-like object formed of the thermosetting resin composition onto the other surface of the electric element, followed by heating and compression.

21. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein the electric element is sealed with the thermosetting resin composition by applying an uncured paste-like object formed of the thermosetting resin composition from the other surface of the electric element under a vacuum or a reduced pressure, followed by heating.

22. (Original) The method for manufacturing the electric element built-in module according to claim 21, wherein the heating is carried out at an atmospheric pressure or larger.

23. (Previously Presented) The method for manufacturing the electric element built-in module according to claim 20, wherein the thermosetting resin composition contains at least a thermosetting resin, and a temperature of the heating is equal to or lower than a cure starting temperature of the thermosetting resin.

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24. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein the thermosetting resin composition contains at least 70wt% to 95wt% of an inorganic filler and 5wt% to 30wt% of a thermosetting resin.

25. (Original) The method for manufacturing the electric element built-in module according to claim 15, further comprising making a division into a desired shape, after grinding or abrading the electric element sealed with the thermosetting resin composition.

26. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein the wiring pattern is formed on a surface of a circuit board.

27. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein the wiring pattern is formed on a surface of a support.

28. (Original) The method for manufacturing the electric element built-in module according to claim 27, wherein the support is formed of an organic film or a metal foil.

29. (Original) The method for manufacturing the electric element built-in module according to claim 27, further comprising peeling off the support, after grinding or abrading the electric element sealed with the thermosetting resin composition.

30. (Original) The method for manufacturing the electric element built-in module according to claim 29, further comprising, after peeling off the support, forming a wiring pattern by laminating a prepreg for a circuit board provided with a through hole in a thickness direction filled with an electrically conductive paste and a metal foil in this order on a surface on a side of the wiring pattern exposed by the peeling, followed by heating and compression, and then etching the metal foil.

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31. (Original) The method for manufacturing the electric element built-in module according to claim 27, further comprising, after sealing the electric element with the thermosetting resin composition and before grinding or abrading the electric element sealed with the thermosetting resin composition,

peeling off the support, and

forming a wiring pattern by laminating a prepreg for a circuit board provided with a through hole in a thickness direction filled with an electrically conductive paste and a metal foil in this order on a surface on a side of the wiring pattern exposed by the peeling, followed by heating and compression, and then etching the metal foil.

32. (Previously Presented) The method for manufacturing the electric element built-in module according to claim 30, further comprising, after forming the wiring pattern by etching the metal foil, forming at least one second wiring pattern by laminating a prepreg for a circuit board provided with a through hole in a thickness direction filled with an electrically conductive paste and a second metal foil in this order on a surface on a side of the wiring pattern obtained by the etching, followed by heating and compression, and then etching the second metal foil.

33. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein the electric element and the thermosetting resin composition are ground or abraded at the same time so as to be substantially flush with each other.

34. (Original) The method for manufacturing the electric element built-in module according to claim 15, wherein the grinding or abrading is carried out by an abrading method using an abrasive.

35. (Previously Presented) The method for manufacturing the electric element built-in module according to claim 21, wherein the thermosetting resin composition contains at least a thermosetting resin, and a temperature of the heating is equal to or lower than a cure starting temperature of the thermosetting resin.

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36. (Previously Presented) The method for manufacturing the electric element built-in module according to claim 31, further comprising, after forming the wiring pattern by etching the metal foil, forming at least one second wiring pattern by laminating a prepreg for a circuit board provided with a through hole in a thickness direction filled with an electrically conductive paste and a second metal foil in this order on a surface on a side of the wiring pattern obtained by the etching, followed by heating and compression, and then etching the second metal foil.